

Amendments to the Claims:

Please amend claims 21 – 24, 29, and 30 as follows. This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. – 20. (Canceled)

21. (Currently Amended) A thermoplastic material suitable for sealing a part of a conducting material and a semiconductor element electrically coupled with the conducting material,

wherein the thermoplastic material has thermoplastic properties and a linear thermal expansion coefficient of $6.0 \times 10^{-5} [1/^{\circ}\text{C}]$ or less at a temperature of 80°C to 130°C .

22. (Currently Amended) A thermoplastic material according to claim 21, wherein ~~a line~~ the linear thermal expansion is coefficient $4.75 \times 10^{-5} [1/^{\circ}\text{C}]$ or less at a temperature of 150°C to 200°C .

23. (Currently Amended) A thermoplastic material according to claim 21, wherein ~~a line~~ the linear thermal expansion coefficient ratio between a flow direction and a normal direction of the flow direction is 0.55 or more.

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24. (Currently Amended) A thermoplastic material according to claim 21, wherein the thermoplastic material composition has a bending strength after solidification ~~[[of]]~~ is 74 MPa or more.

25. (Previously Presented) A thermoplastic material according to claim 21, wherein an adhesion imparting agent is added to improve adhesion properties to another material by binding with a polar group.

26. (Previously Presented) A thermoplastic material according to claim 21, further containing silica particles.

27. (Previously Presented) A thermoplastic material according to claim 21, wherein the thermoplastic material is substantially free of a fibrous material.

28. (Previously Presented) A thermoplastic material according to claim 21, wherein the thermoplastic material is substantially free of a thermosetting material.

29. (Currently Amended) A thermoplastic material according to claim 21, wherein a product obtained by multiplying a value of a ~~[[line]]~~ linear expansion at 25 to 80°C plus ~~a line~~ the linear thermal expansion coefficient at 80 to 125°C after solidification, by a bending strength ~~[[is]]~~ of 25 MPa or less.

30. (Currently Amended) A thermoplastic material for sealing a semiconductor element, wherein the thermoplastic material has thermoplastic properties and [[a]] the linear thermal expansion coefficient of $6.0 \times 10^{-5}[1/^{\circ}\text{C}]$ or less at a temperature of 80°C to 130°C .

31. (Previously Presented) A process for manufacturing a semiconductor device comprising:

electrically interconnecting a semiconductor element with one end of a conducting material; and

sealing the semiconductor element and the one end of the conducting material with a thermoplastic material according to claim 21.

32. (Previously Presented) A process for manufacturing a semiconductor device comprising:

electrically interconnecting a semiconductor element with one end of a conducting material; and

sealing the semiconductor element and the one end of the conducting material with a thermoplastic material according to claim 30.

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